

# **N-Channel Super Trench Power MOSFET**

#### **Description**

The RM110N85T2 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

#### **General Features**

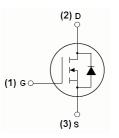
- $V_{DS}$  =85V, $I_{D}$  =110A  $R_{DS(ON)}$  <6mΩ @  $V_{GS}$ =10V
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

## **Application**

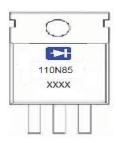
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

100% UIS TESTED!

100% ∆Vds TESTED!



Schematic diagram



Marking and pin assignment



TO-220-3L top view

## **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Device Package	Reel Size	Tape width	Quantity
110N85	RM110N85T2	TO-220-3L	-	-	-

## Absolute Maximum Ratings (T<sub>C</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	85	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	110	А
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	81	А
Pulsed Drain Current	I <sub>DM</sub>	320	А
Maximum Power Dissipation	P <sub>D</sub>	145	W
Derating factor		0.97	W/℃
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	700	mJ
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	°C

## **Thermal Characteristic**

Thermal Resistance, Junction-to-Case (Note 2)	$R_{ heta JC}$	1.03	°C/W
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# Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	·		•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	85		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =85V,V <sub>GS</sub> =0V	-	-	1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	2.5	3.3	4.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =55A	-	5	6	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V,I <sub>D</sub> =55A	40	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C <sub>lss</sub>	V <sub>DS</sub> =40V,V <sub>GS</sub> =0V, F=1.0MHz	-	3870	-	PF
Output Capacitance	Coss		-	500	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVIHZ	-	43	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	18	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =40V, $I_D$ =55A	-	8	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10V, $R_{G}$ =4.7 $\Omega$	-	28	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	8	-	nS
Total Gate Charge	Qg	\/ -40\/  -55A	-	54		nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =40 $V$ , $I_{D}$ =55 $A$ ,	-	20		nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =10V	-	9		nC
Drain-Source Diode Characteristics	<u> </u>					•
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =110A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	110	А
Reverse Recovery Time	t <sub>rr</sub>	$T_J = 25^{\circ}C$ , $I_F = I_S$	-	70		nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	165		nC

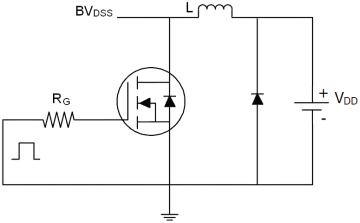
#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25  $^{\circ}\text{C}$  ,V\_DD=42.5V,V\_G=10V,L=0.5mH,Rg=25 $\Omega$

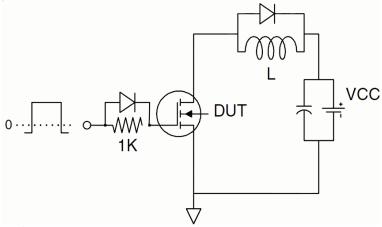


## **Test Circuit**

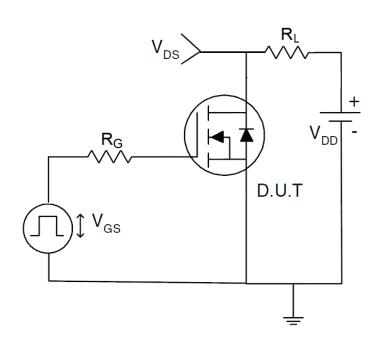
# 1) E<sub>AS</sub> test Circuit



# 2) Gate charge test Circuit

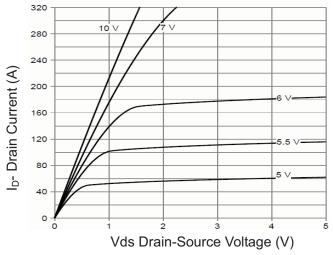


# 3) Switch Time Test Circuit

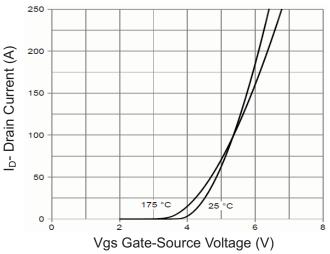




# **RATING AND CHARACTERISTICS CURVES (RM110N85T2)**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

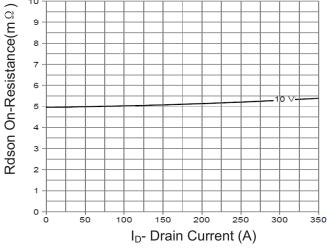


Figure 3 Rdson- Drain Current

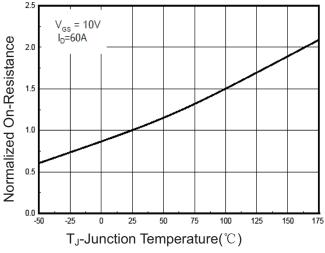


Figure 4 Rdson-JunctionTemperature

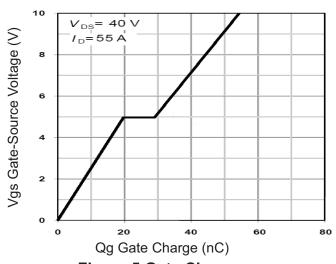


Figure 5 Gate Charge

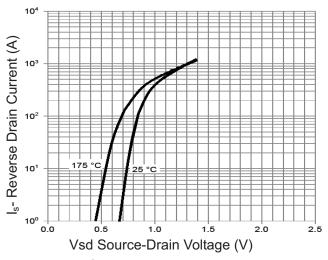
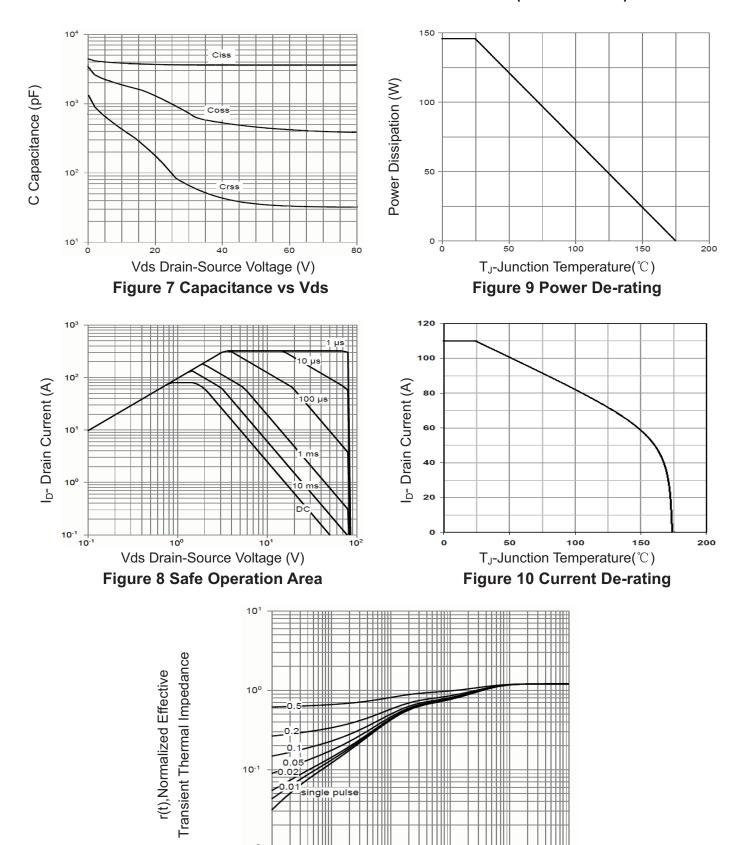


Figure 6 Source- Drain Diode Forward



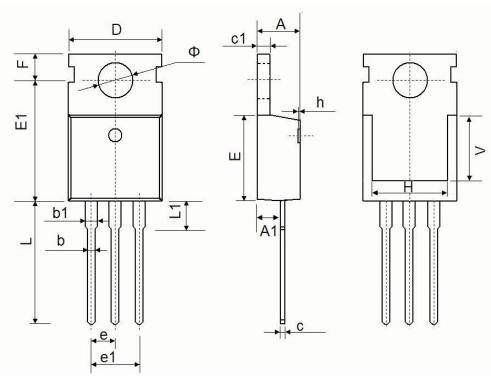
## **RATING AND CHARACTERISTICS CURVES (RM110N85T2)**



Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

# **TO-220-3L Package Information**



Currele e l	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540 TYP.		0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.500 REF.		0.295 REF.		
Ф	3.400	3.800	0.134	0.150	



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